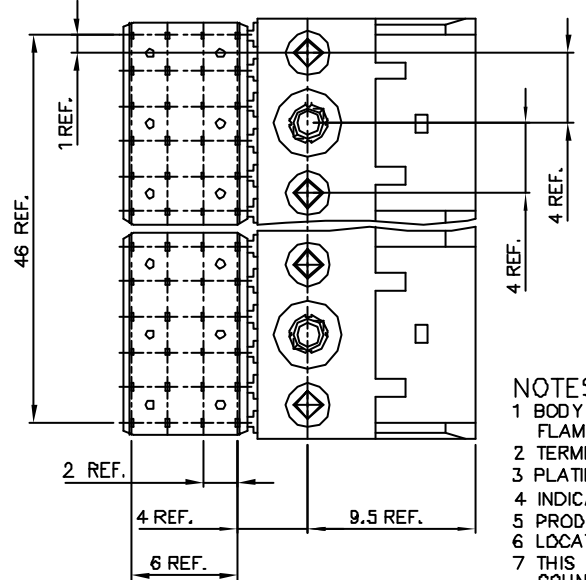
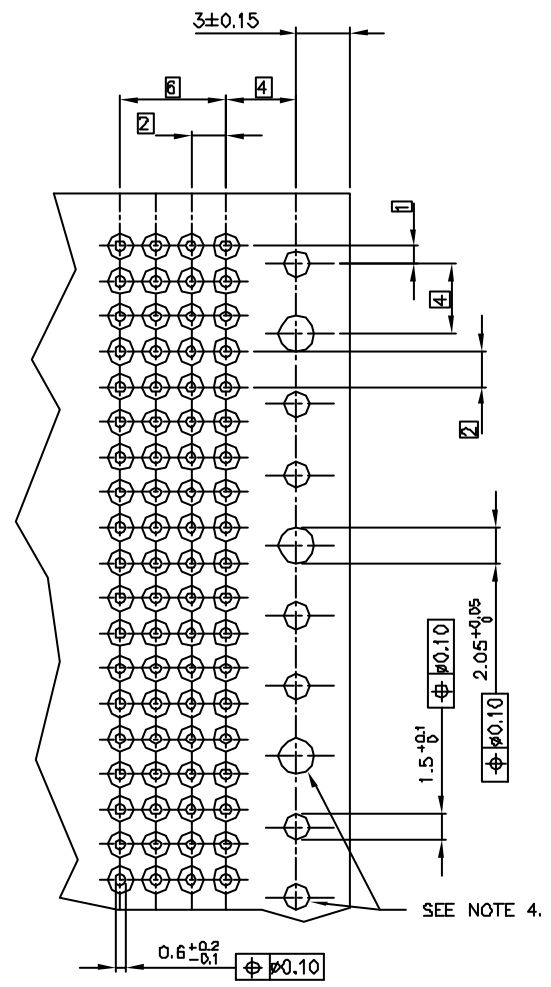
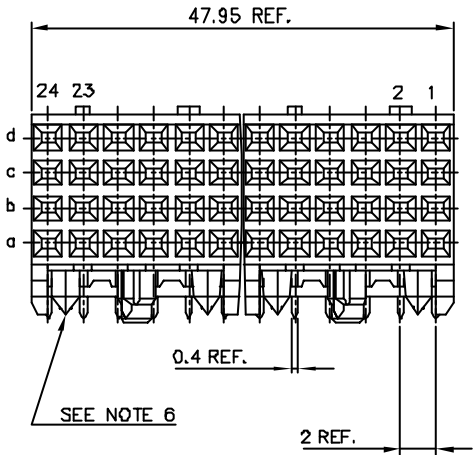
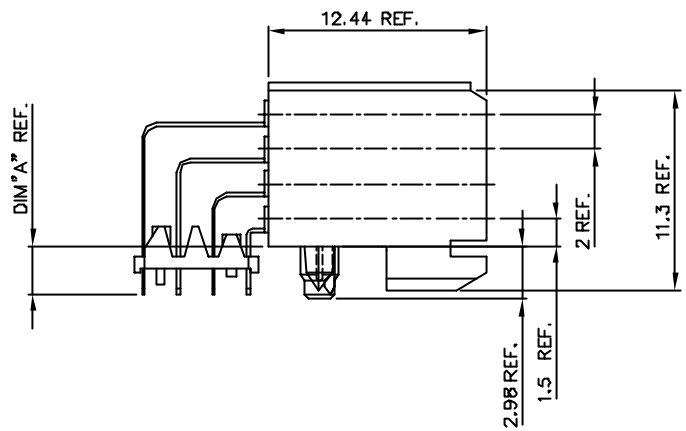
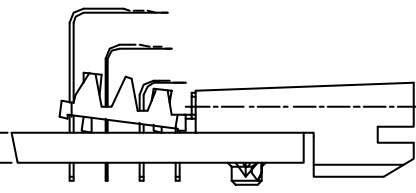


PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89037-X01/X01LF	1.6	2.73
89037-X11/X11LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.



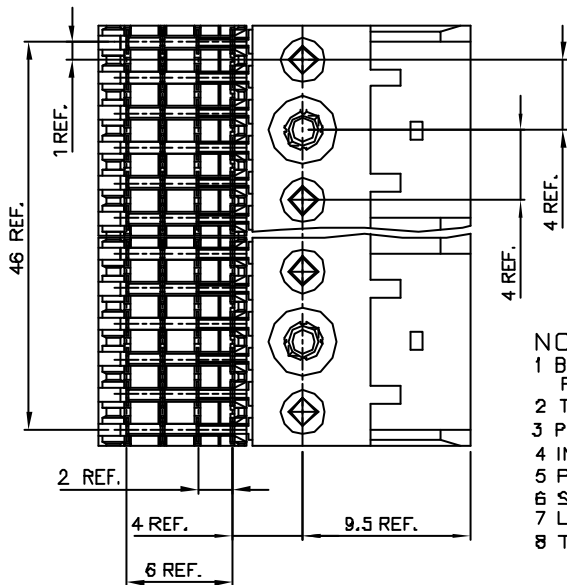
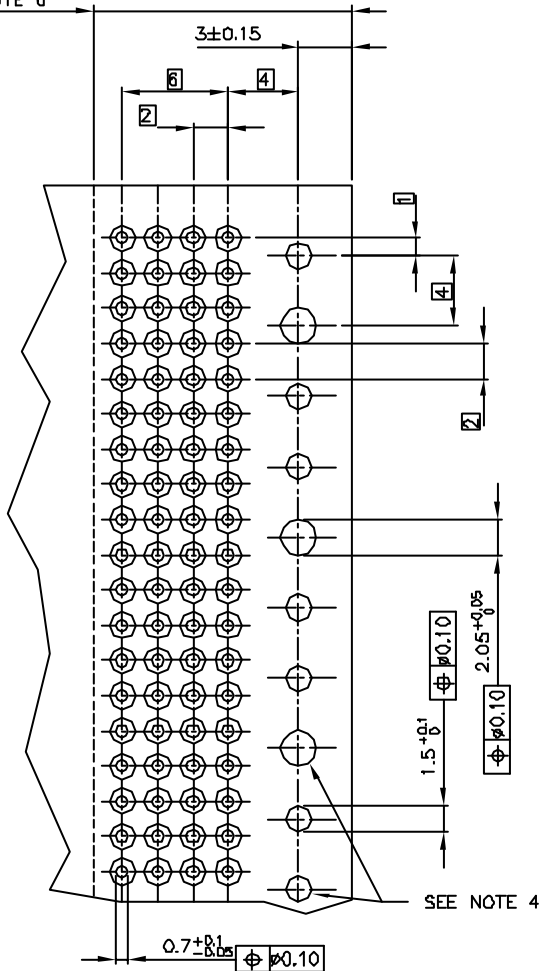
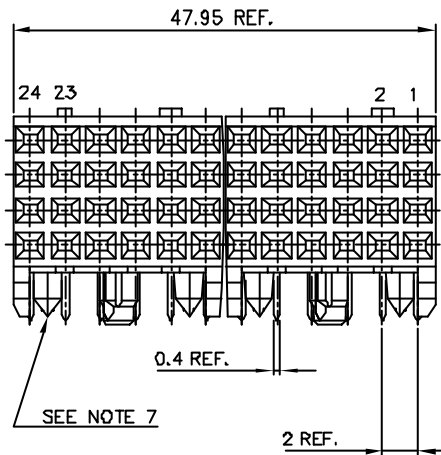
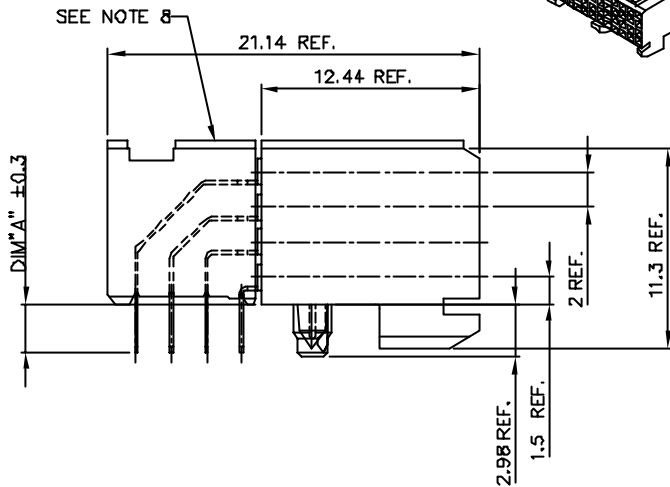
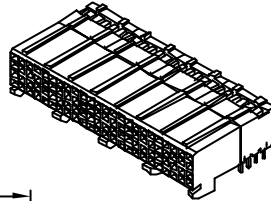
- NOTES:**
- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS  
FLAME RETARDANT ACC. UL 94-V0
  - 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
  - 3 PLATING SOLDERTAILS 2-8  $\mu$ m SnPb 90-97 OR 2-8  $\mu$ m PURE Sn
  - 4 INDICATED HOLES ARE UNPLATED.
  - 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
  - 6 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
  - 7 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
  - 8 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89037-1YZ/1YZLF	0.8 $\mu$ m GOLD	1.3 $\mu$ m Ni MIN.
89037-2YZ/2YZLF	2 $\mu$ m GOLD	1.3 $\mu$ m Ni MIN.
89037-3YZ/3YZLF	1.3 $\mu$ m GOLD	1.3 $\mu$ m Ni MIN.
89037-9YZ/9YZLF	0.8 $\mu$ m GXT	1.3 $\mu$ m Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER		ELECTRONICS	
itr	can no	dr	date	linear	projection	title	www.electronics.com
J	8904-0104	CU	041221			RA FEMALE SIGNAL	
D	H40-355	008	0410027	angles		48 mm PRESS PEC	
F	V70769	008	070530	dr	H.Boenknecht	product form	215
F	V81480	008	090827	eng	Pl. Baumkamp	size	1 of 2
S	V00078	008	000318	chr	S.Lee	dwg no	
N	V00047	008	000530	appl	J.W. Jones	89037	
sheet	revision	J	J				
index	sheet	1	2				

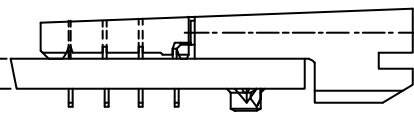
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PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89037-X02/X02LF	1.6	2.73
89037-X12/X12LF	2.4	3.53



PC BOARD THICKNESS ±0.20  
SEE TABLE

PRODUCT AFTER PC BOARD APPLICATION.



- NOTES:
- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS  
FLAME RETARDANT ACC. UL 94-V0
  - 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
  - 3 PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn
  - 4 INDICATED HOLES ARE UNPLATED.
  - 5 PRODUCT MARKING: PART NUMBER & BATCH ID.
  - 6 SET BACK FOR PRESS BLOCK.
  - 7 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
  - 8 TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD
  - 9 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-D08
  - 10 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
B9037-1YZ/1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
B9037-2YZ/2YZLF	2 µm GOLD	1.3 µm Ni MIN.
B9037-3YZ/3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
B9037-9YZ/9YZLF	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER		ELECTRONICS	
itr	can no	dr	date	GDPY	projection	title	www.electronics.com
J					1st angle	48 mm FEMALE SIGNAL PRESS PCB	
					mm	product form METRAL (µm)	code 213
					scale 1:1	size dwg no	sheet 2 of 2
					A2	89037	
sheet index	revision sheet						

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